

IGBT Modules

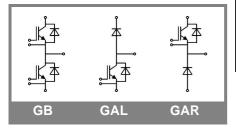
SKM 75GB123D SKM 75GAL123D SKM 75GAR123D

Features

- MOS input (voltage controlled)
- Low inductance case
- Very low tail current with low temperature dependence
- High short circuit capability, self limiting to 6 x I_{cnom}
- · Latch-up free
- Fast & soft inverse CAL diodes
- Isolated copper baseplate using **DCB Direct Copper Bonding** Technology
- Large clearance (10 mm) and creepage distance (20 mm)

Typical Applications

- AC inverter drives
- UPS



Absolute Maximum Ratings T _c = 25 °C, unless otherwise specific				
Symbol			Values	Units
IGBT				
V_{CES}	T _j = 25 °C T _i = 150 °C		1200	V
I _C	T _j = 150 °C	T _{case} = 25 °C	75	Α
		T _{case} = 80 °C	60	Α
I _{CRM}	I _{CRM} =2xI _{Cnom}		150	Α
V_{GES}			± 20	V
t _{psc}	V_{CC} = 600 V; $V_{GE} \le 20$ V; VCES < 1200 V	T _j = 125 °C	10	μs
Inverse D	Diode			
I_{F}	T _j = 150 °C	T_{case} = 25 °C	75	Α
		T_{case} = 80 °C	50	Α
I _{FRM}	I _{FRM} =2xI _{Fnom}		150	Α
I _{FSM}	$t_p = 10 \text{ ms}; \sin.$	T _j = 150 °C	480	Α
Freewhe	eling Diode		•	
I_{F}	T _j = 150 °C	T_{case} = 25 °C	95	Α
		T _{case} = 80 °C	65	Α
I_{FRM}	I _{FRM} =2xI _{Fnom}		200	Α
I _{FSM}	$t_p = 10 \text{ ms}; \sin$	T _j = 150 °C	720	Α
Module			•	
$I_{t(RMS)}$			200	Α
T _{vj}			- 40+ 150	°C
T _{stg}			- 40+ 125	°C
V _{isol}	AC, 1 min.		2500	V

Characteristics T _c =		25 °C, unless otherwise specified				
Symbol	Conditions		min.	typ.	max.	Units
IGBT						
$V_{GE(th)}$	$V_{GE} = V_{CE}$, $I_{C} = 2 \text{ mA}$		4,5	5,5	6,5	V
I _{CES}	$V_{GE} = 0 V, V_{CE} = V_{CES}$	T _j = 25 °C T _i = 25 °C		0,1	0,3	mA
V _{CE0}		T _j = 25 °C		1,4	1,6	V
		T _j = 125 °C		1,6	1,8	V
r _{CE}	V _{GE} = 15 V	T _j = 25°C		22	28	mΩ
		T _j = 125°C		30	38	$m\Omega$
V _{CE(sat)}	I _{Cnom} = 50 A, V _{GE} = 15 V	T _j = °C _{chiplev.}		2,5	3	V
C _{ies}				3,3	4,3	nF
C _{oes}	$V_{CE} = 25, V_{GE} = 0 V$	f = 1 MHz		0,5	0,6	nF
C _{res}				0,22	0,3	nF
Q_G	V _{GE} = -8 - +20V			500		nC
R _{Gint}	$T_j = {^{\circ}C}$			5		Ω
t _{d(on)}				44	100	ns
t _r	$R_{Gon} = 22 \Omega$	V _{CC} = 600V		56	100	ns
E _{on}		I _C = 50A		8		mJ
t _{d(off)}	$R_{Goff} = 22 \Omega$	T _j = 125 °C		380	500	ns
t _f		$V_{GE} = \pm 15V$		70	100	ns
E _{off}				5		mJ
$R_{th(j-c)}$	per IGBT				0,27	K/W



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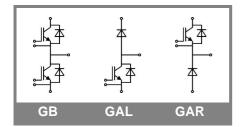
Typical Applications

- AC inverter drives
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Characte	Characteristics						
Symbol	Conditions		min.	typ.	max.	Units	
Inverse D							
$V_F = V_{EC}$	$I_{Fnom} = 50 \text{ A}; V_{GE} = 0 \text{ V}$	$T_j = 25 ^{\circ}C_{\text{chiplev.}}$		2	2,5	V	
		$T_j = 125 ^{\circ}\text{C}_{\text{chiplev.}}$ $T_j = 25 ^{\circ}\text{C}$		1,8		V	
V_{F0}				1,1	1,2	V	
		T _j = 125 °C				V	
r _F		T _j = 25 °C		18	26	mΩ	
		T _j = 125 °C				mΩ	
I _{RRM}	I _F = 50 A	T _j = 125 °C		35		A	
Q _{rr}	di/dt = 800 A/µs					μC	
E _{rr}	V _{GE} = 0 V; V _{CC} = 600 V					mJ	
R _{th(j-c)D}	per diode				0,6	K/W	
	eling Diode						
$V_F = V_{EC}$	I_{Fnom} = 50 A; V_{GE} = 0 V			1,85	2,2	V	
		$T_j = 125 ^{\circ}C_{\text{chiplev.}}$		1,6		V	
V_{F0}		T _j = 25 °C		1,1	1,2	V	
		T _j = 125 °C				V	
r _F		T _j = 25 °C		15	20	V	
		T _j = 125 °C				V	
I _{RRM}	I _F = 50 A	T _j = 125 °C		40		A	
Q _{rr}	.,,					μC	
E _{rr}	V _{GE} = 0 V; V _{CC} = 600 V					mJ	
$R_{th(j-c)FD}$	per diode				0,5	K/W	
Module							
L _{CE}					30	nΗ	
R _{CC'+EE'}	res., terminal-chip	T _{case} = 25 °C		0,75		mΩ	
		T _{case} = 125 °C		1		$m\Omega$	
R _{th(c-s)}	per module				0,05	K/W	
M_s	to heat sink M6		3		5	Nm	
M_t	to terminals M5		2,5	_	5	Nm	
w					160	g	

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

This technical information specifies semiconductor devices but promises no characteristics. No warranty or guarantee expressed or implied is made regarding delivery, performance or suitability.





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Features

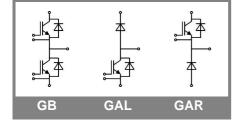
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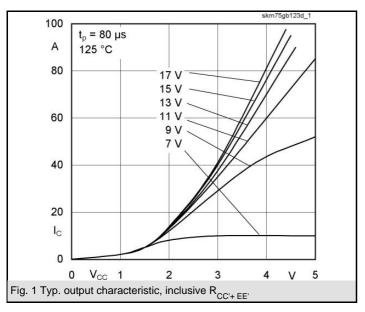
Typical Applications

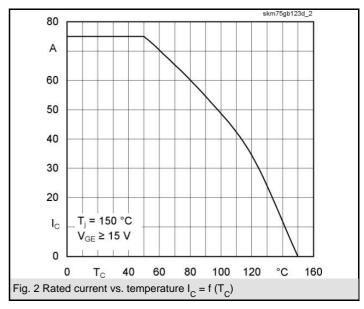
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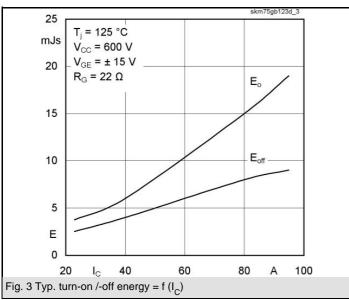
Z _{th} Symbol	Conditions	Values	Units
Z _{Ri} th(j-c)l			
R _i	i = 1	180	mk/W
R _i	i = 2	64	mk/W
Ri	i = 3	22	mk/W
R _i	i = 4	4	mk/W
tau _i	i = 1	0,0327	s
tau _i	i = 2	0,0479	s
tau _i	i = 3	0,008	s
tau _i	i = 4	0,005	s
Z,,,,,,,,,,,	•		
Z Rith(j-c)D	i = 1	380	mk/W
R _i	i = 2	190	mk/W
R _i	i = 3	26	mk/W
R _i	i = 4	4	mk/W
tau _i	i = 1	0,0947	s
taui	i = 2	0,006	s
tau _i	i = 3	0,08	s
tau _i	i = 4	0,003	s

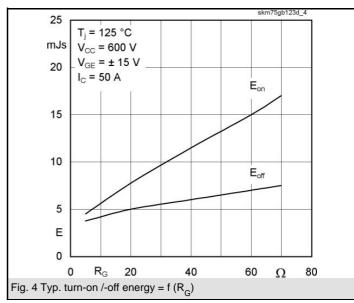
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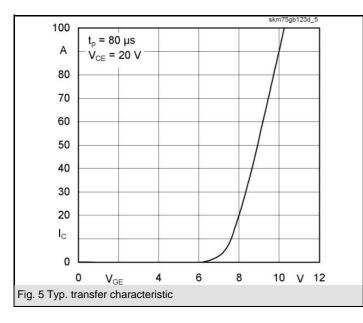


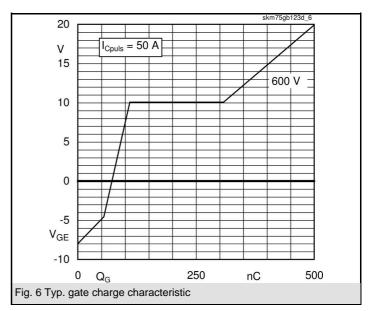


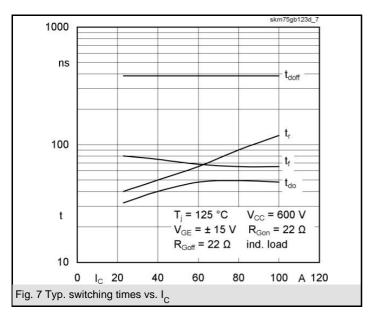


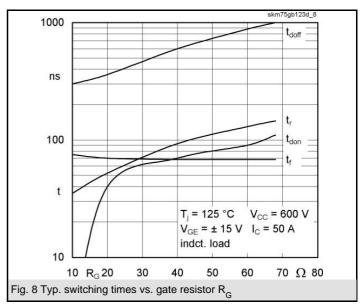


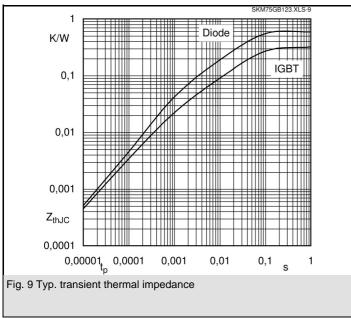


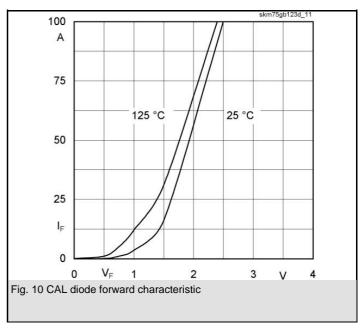


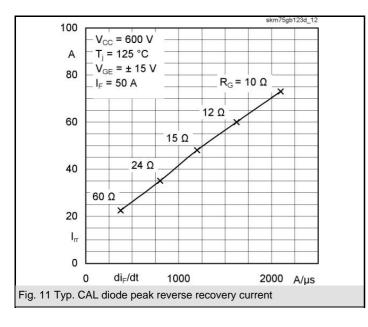


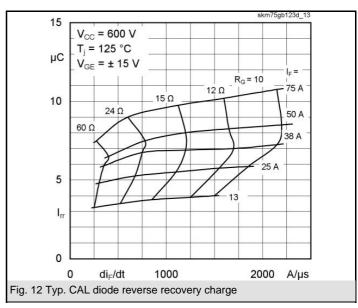






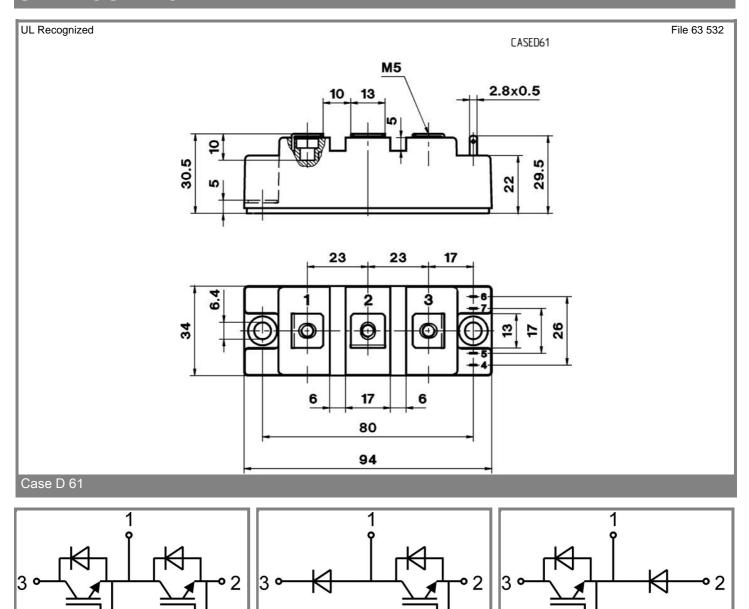






Case D 61

GAL



Case D 62 (→ D 61)

GAR

Case D 63 (→ D 61)